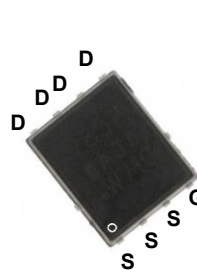
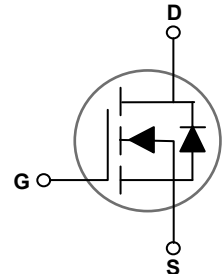


## Main Product Characteristics

$BV_{DSS}$	65V
$R_{DS(ON)}$	16m $\Omega$
$I_D$	44A



PPAK 5x6



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSGP6988 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	+20/-12	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	44	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		27	A
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	176	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	9.1	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	13.5	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	54.3	W
Power Dissipation-Derate above $25^\circ\text{C}$		0.43	W/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.3	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

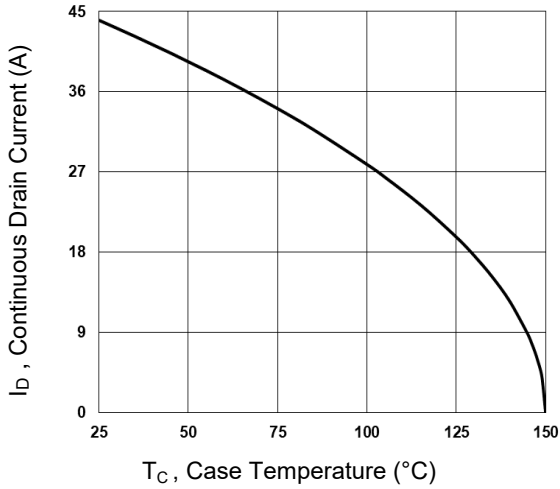
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	65	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$	-	0.03	-	$V/^{\circ}\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=60V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	-	-	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_J=85^{\circ}\text{C}$	-	-	10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=+20V, V_{DS}=0V$	-	-	100	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=16A$	-	13.6	16	$m\Omega$
		$V_{GS}=4.5V, I_D=12A$	-	24.5	30	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1	1.6	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-5.1	-	$mV/^{\circ}\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=10V, I_D=3A$	-	5	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3, 4</sup>	$Q_g$	$V_{DS}=30V, V_{GS}=10V, I_D=12A$	-	10.9	22	nC
Gate-Source Charge <sup>3, 4</sup>	$Q_{gs}$		-	1.5	3	
Gate-Drain Charge <sup>3, 4</sup>	$Q_{gd}$		--	4.4	9	
Turn-On Delay Time <sup>3, 4</sup>	$T_{d(on)}$	$V_{DD}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=1A$	-	8	16	nS
Rise Time <sup>3, 4</sup>	$T_r$		-	12	24	
Turn-Off Delay Time <sup>3, 4</sup>	$T_{d(off)}$		-	25	50	
Fall Time <sup>3, 4</sup>	$T_f$		-	18	36	
Input Capacitance	$C_{iss}$	$V_{DS}=30V, V_{GS}=0V, F=1\text{MHz}$	-	653	1300	pF
Output Capacitance	$C_{oss}$		-	192	380	
Reverse Transfer Capacitance	$C_{rss}$		-	27	60	
Gate Resistance	$R_g$	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$	-	0.3	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	-	-	44	A
Pulsed Source Current <sup>3</sup>	$I_{SM}$		-	-	88	A
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	-	-	1	V

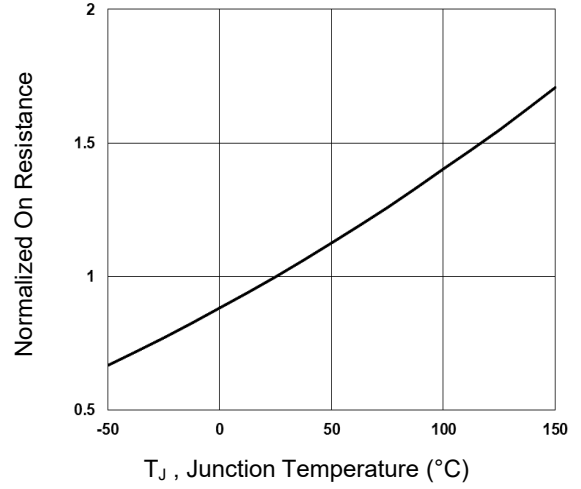
Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=50V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=13.5A, R_G=25\Omega, \text{Starting } T_J=25^{\circ}\text{C}$ .
3. Pulse test, pulse width  $\leq 300\mu\text{S}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

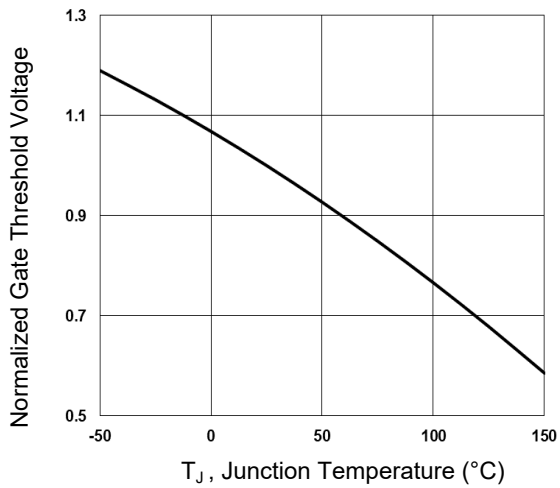
**Typical Electrical and Thermal Characteristic Curves**



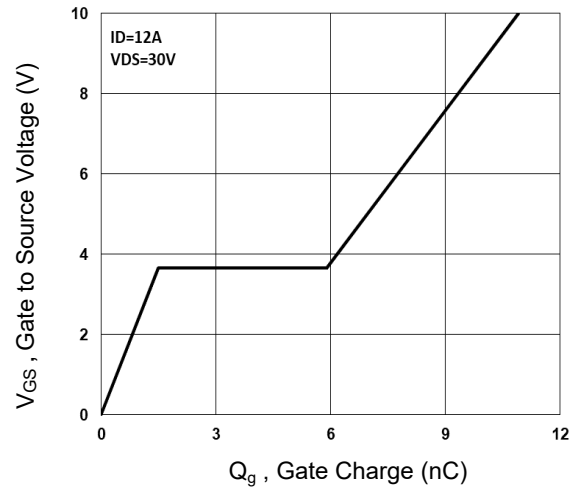
**Figure 1. Continuous Drain Current vs.  $T_C$**



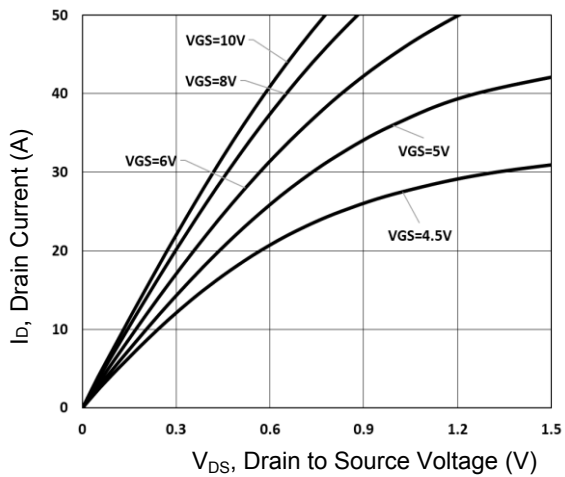
**Figure 2. Normalized  $R_{DSON}$  vs.  $T_J$**



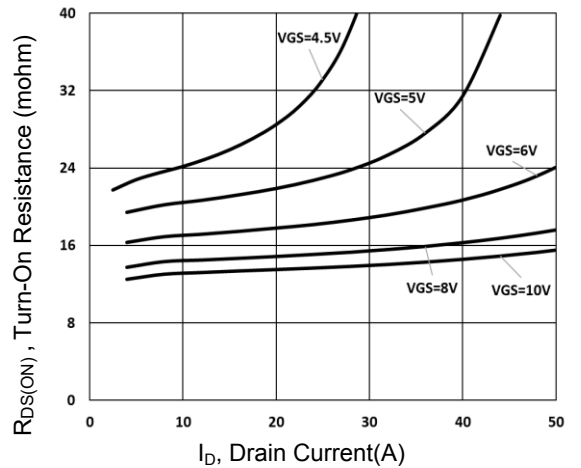
**Figure 3. Normalized  $V_{th}$  vs.  $T_J$**



**Figure 4. Gate Charge Waveform**

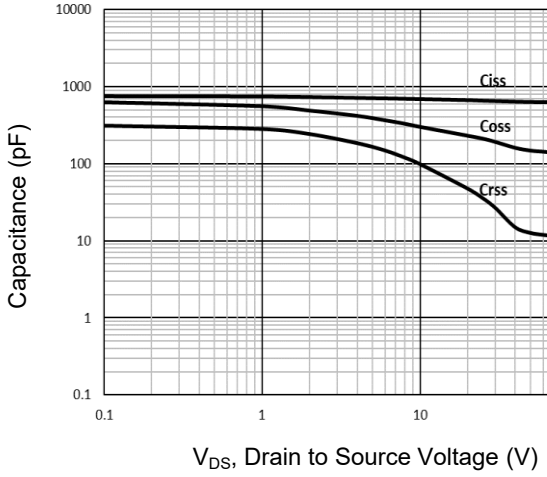


**Figure 5. Typical Output Characteristics**

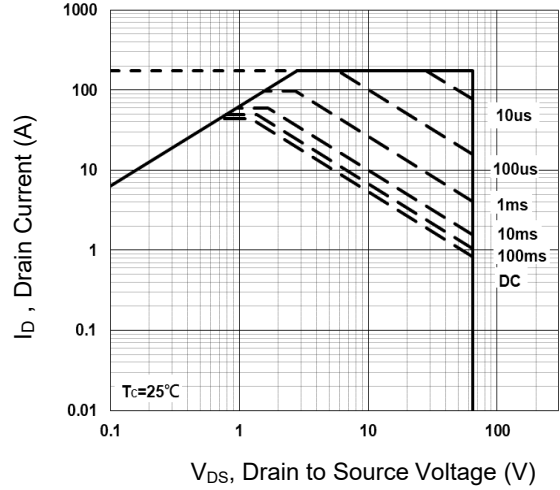


**Figure 6. Turn-On Resistance vs.  $I_D$**

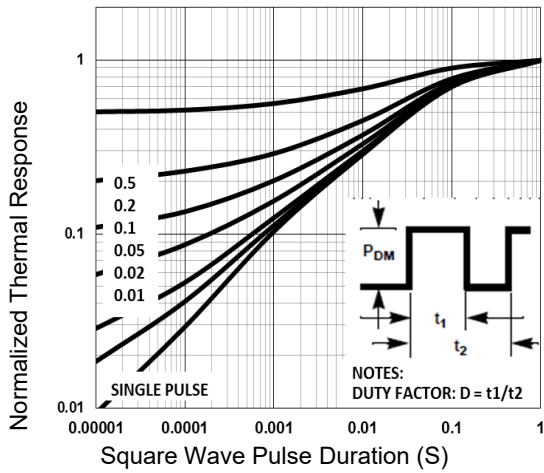
**Typical Electrical and Thermal Characteristic Curves**



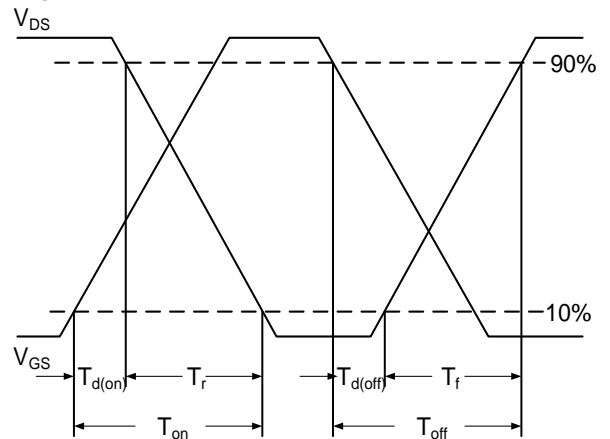
**Figure 7. Capacitance Characteristics**



**Figure 8. Maximum Safe Operation Area**

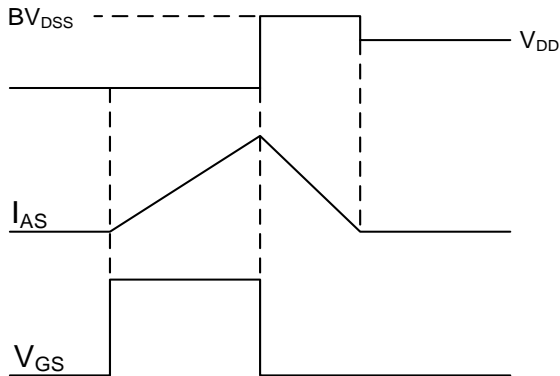


**Figure 9. Normalized Transient Response**



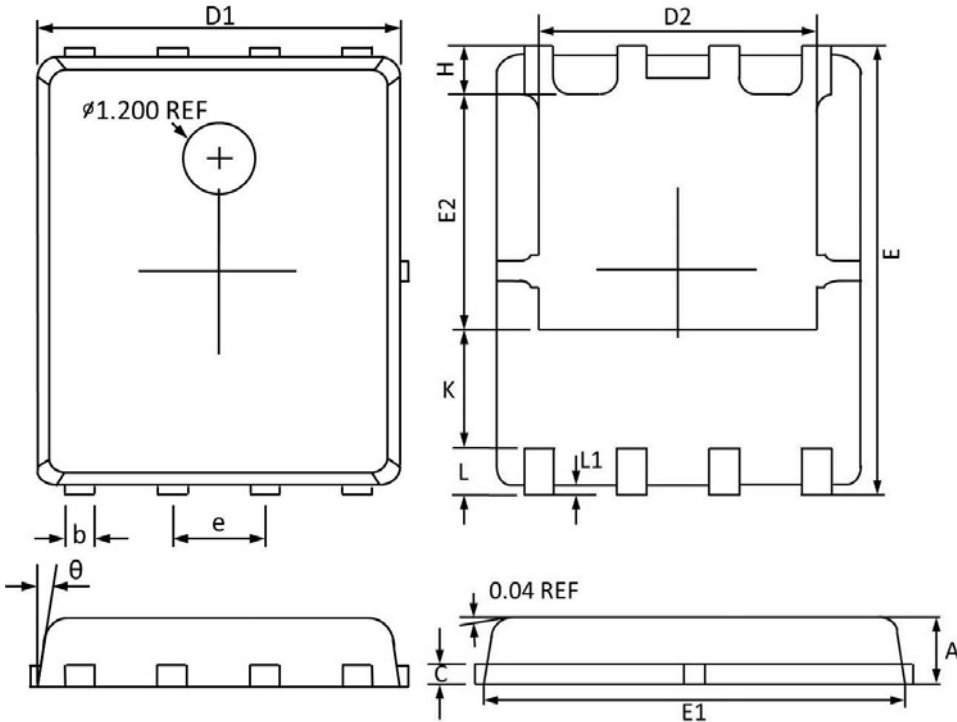
**Figure 10. Switching Time Waveform**

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$



**Figure 11. E<sub>AS</sub> Waveform**

**Package Outline Dimensions PPAK5x6**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°